ABSTRACT OF THE DISCLOSURE

A hybrid device is formed by bonding together a substrate on which a micromachine (MEMS) is formed, and a semiconductor layer on which a semiconductor device is formed through an adhesion layer. The semiconductor layer can be formed by, e.g., bonding together the substrate and a member which has a separation layer (e.g., a porous layer) under the semiconductor layer on which the semiconductor device is formed, and then dividing the member at the separation layer. Alternatively, the hybrid device includes a semiconductor layer on which a circuit is formed and an antenna substrate on which an antenna is formed. The semiconductor layer and antenna substrate are bonded together, and the semiconductor layer is formed by separating, at a separation layer, a substrate which includes the separation layer.